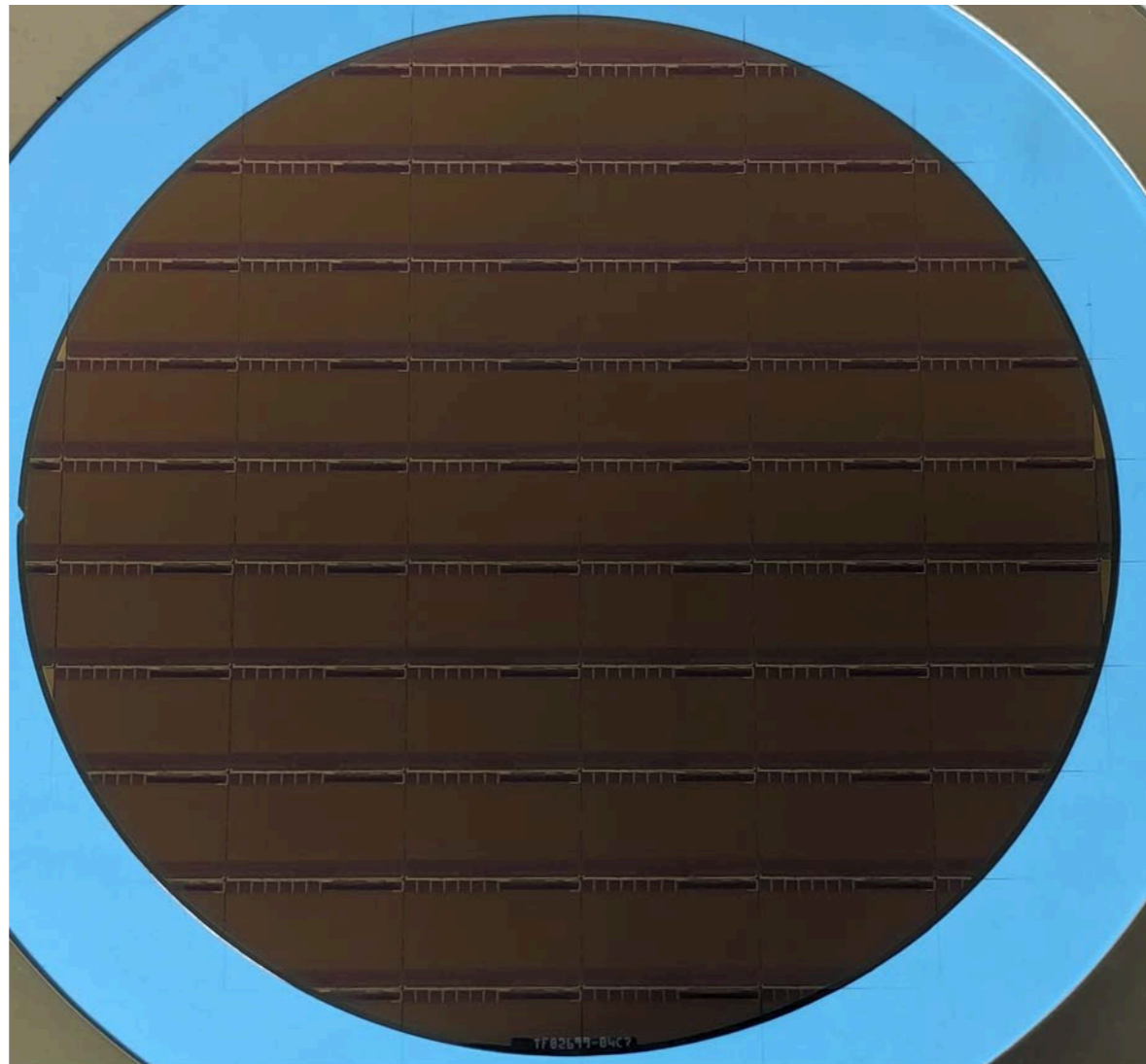
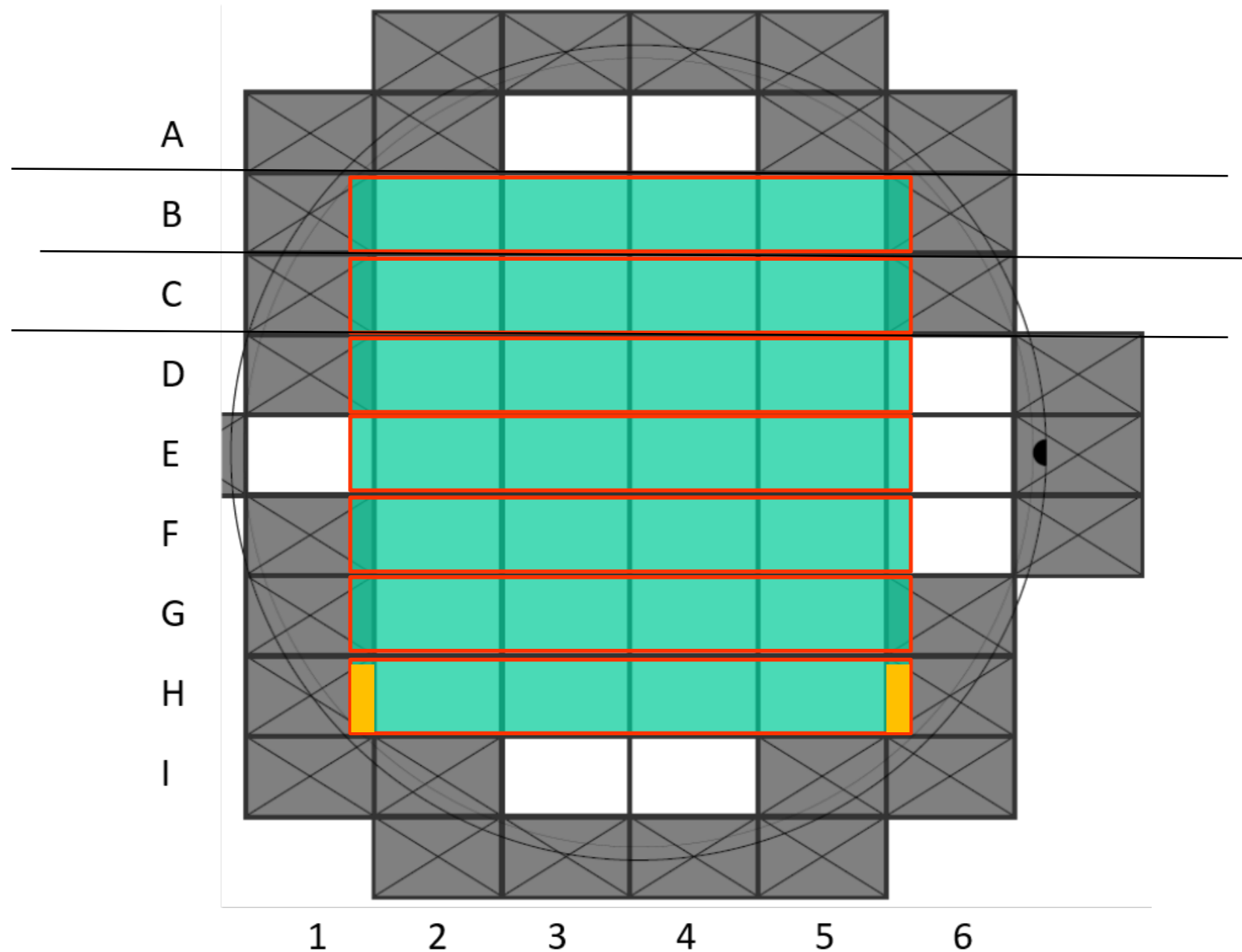


# iVTX Dummy Module Dicing

- Goal : Have samples of 14\*2 cm thin to about 100 $\mu$ m to test the gluing on TPG for thermal studies à IJClab (See Julien's slides)
- Using Mimosis Pad wafer



Excercise do by  
MicroPacks company  
(South of France)



Dice size ~19.67 mm \* 140 mm  
Thinning tickness ~100-150 $\mu$ m





Due to Double Use restriction  
the PAD samples can not be send  
outside of France

- 6 pads samples at 100 $\mu$ m thick
- 4 silicium samples at 100 $\mu$ m Thick
- 6 silicium samples at 150 $\mu$ m Thick